

Title (en)

COPPER ALLOY MATERIAL FOR ELECTRIC AND ELECTRONIC COMPONENTS

Title (de)

KUPFERLEGIERUNGSMATERIAL FÜR ELEKTRISCHE UND ELEKTRONISCHE BAUTEILE

Title (fr)

MATÉRIAU D'ALLIAGE DU CUIVRE POUR COMPOSANTS ÉLECTRIQUES ET ÉLECTRONIQUES

Publication

EP 2267172 A1 20101229 (EN)

Application

EP 09722228 A 20090319

Priority

- JP 2009055531 W 20090319
- JP 2008074650 A 20080321

Abstract (en)

A copper alloy material for an electric/electronic part, containing Co 0.5 to 2.5 mass% and Si 0.1 to 1.0 mass%, at a ratio of Co/Si of 3 to 5 in terms of mass ratio, with the balance of Cu and inevitable impurities, which is obtained by subjecting to a solution treatment at a temperature (°C) from 800°C to 960°C and lower than $-122.77X + 409.99X + 615.74$, in which X represents the Co content in mass%.

IPC 8 full level

C22C 9/06 (2006.01); **C22F 1/00** (2006.01); **C22F 1/08** (2006.01); **H01B 1/02** (2006.01)

CPC (source: EP US)

C22C 9/06 (2013.01 - EP US); **C22F 1/08** (2013.01 - EP US); **H01B 1/026** (2013.01 - EP US)

Citation (search report)

See references of WO 2009116649A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA RS

DOCDB simple family (publication)

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JP WO2009116649 A1 20110721; US 2011005644 A1 20110113; WO 2009116649 A1 20090924

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EP 09722228 A 20090319; CN 200980110059 A 20090319; JP 2009055531 W 20090319; JP 2010503942 A 20090319;
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